

LISTING OF THE CLAIMS

1. (Previously Presented) A liquid crystal display device including a data line supplied with a data signal, a gate line supplied with a scanning signal, a pixel electrode for driving a liquid crystal cell, and a thin film transistor for applying the data signal to the pixel electrode in response to the scanning signal, the device comprising:

a gate insulating film entirely covering the gate line wherein the data line is disposed on the gate insulating film, and wherein the gate line is disposed directly on a substrate;

a storage electrode sunken in the gate insulating film to overlap with the gate line, said storage electrode uncovered by and disposed upon said gate insulating film; and

a protective layer on the gate insulating film to cover the data line, the gate line and the thin film transistor,

wherein a contact hole passes through the protective layer and a portion of the gate insulating film having the storage electrode sunken therein, the pixel electrode is connected to the storage electrode via the contact hole, and the gate insulating film contacts sides of the storage electrode.

2. (Original) The liquid crystal display device according to claim 1, wherein a distance between the gate line and the storage electrode is about 500 to 2500Å.

3. (Canceled)

4. (Canceled)

5. (Original) A method of fabricating a liquid crystal display having a storage electrode, comprising:

forming a gate line and a gate electrode of a thin film transistor on a substrate;

depositing a first gate insulating film on the substrate to cover the gate electrode and the gate line;

forming the storage electrode on the first gate insulating film to overlap with the gate line;

depositing a second gate insulating film on the first gate insulating film to cover the storage electrode;

forming an active layer and an ohmic contact layer on the gate insulating films;

forming a source electrode and a drain electrode of the thin film transistor opposed to each other having a desired channel therebetween on the ohmic contact layer;

forming a protective layer on the gate insulating film to cover the source electrode and the drain electrode;

defining a first contact hole exposing the drain electrode on the protective layer;

defining a second contact hole exposing the storage electrode on the protective layer and the second gate insulating film; and

forming a pixel electrode connected to the drain electrode, via the first contact hole, and connected to the storage electrode on the protective layer, via the second contact hole.

6. (Original) The method according to claim 5, wherein a distance between the gate line and the storage electrode is about 500 to 2500Å.

7. (Previously Presented) A liquid crystal display device comprising:

a gate line and a data line on a substrate to cross each other, wherein the gate line is disposed directly on the substrate;

a thin film transistor including a gate electrode, a source electrode, and a drain electrode, and provided at an intersection between the data line and the gate line;

a storage electrode on a first gate insulating film to cover the gate electrode and the gate line;

a second gate insulating film formed on the first gate insulating film, wherein the data line is disposed on the second gate insulating film so that the gate line is electrically isolated from the data line; and

a protective layer formed on the second gate insulating film to cover the gate line, the data line and the thin film transistor,

wherein a first contact hole passes through the protective layer and a portion of the second gate insulating film having the storage electrode formed on the first gate insulating film, wherein the storage electrode is connected to a transparent electrode pattern via the first contact hole and wherein a storage capacitor includes the storage electrode and the gate line opposed to each other and having the first gate insulating film formed therebetween.

8. (Canceled)

9. (Previously Presented) The liquid crystal display device according to claim 7, further comprising an active layer and an ohmic contact layer formed on the second gate insulating film to overlap with the gate electrode.

10. (Canceled)

11. (Original) The liquid crystal display device according to claim 7, wherein the gate electrode is connected to the gate line.

12. (Original) The liquid crystal display device according to claim 7, wherein the source electrode is connected to the data line.

13. (Original) The liquid crystal display device according to claim 12, wherein the drain electrode is opposed to the source electrode, and wherein a channel is formed between the source electrode and the drain electrode.

14. (Previously Presented) The liquid crystal display device according to claim 7, wherein a pixel electrode is connected to the drain electrode via a second contact hole provided on the protective layer.
15. (Canceled)
16. (Canceled)
17. (Original) A method of fabricating a liquid crystal display, comprising the steps of:
forming a gate line and a gate electrode of a thin film transistor on a substrate;
depositing a first gate insulating film on the substrate to cover the gate electrode and the gate line;
forming a storage electrode on the first gate insulating film to overlap with the gate line;
depositing a second gate insulating film on the first gate insulating film to cover the storage electrode;
forming an active layer and an ohmic contact layer on the gate insulating films;
forming a source electrode and a drain electrode of the thin film transistor opposed to each other having a desired channel therebetween on the ohmic contact layer;
forming a protective layer on the gate insulating film to cover the source electrode and the drain electrode;
forming a pixel electrode connected to the drain electrode; and
forming a transparent electrode pattern connected the storage electrode on the protective layer.
18. (Original) The method according to claim 17, further comprising:
defining a first contact hole for exposing the drain electrode on the protective layer; and
defining a second contact hole for exposing the storage electrode on the protective layer and the second gate insulating film.

19. (Original) The method according to claim 18, wherein the second contact hole is formed to the same thickness as the first contact hole by patterning the second gate insulating film using the protective layer as a mask to expose the storage electrode.
20. (Original) The method according to claim 17, wherein the gate electrode and the gate line are formed by depositing a metal from one of aluminum and copper using sputtering and then patterning the metal.
21. (Original) The method according to claim 17, wherein the first gate insulating film is formed by depositing an insulating material to a thickness of about 500 to 2500 Å using plasma enhanced chemical vapor deposition.
22. (Original) The method according to claim 21, wherein the second gate insulating film is formed to the same thickness of the first gate insulating film.
23. (Original) The method according to claim 17, wherein the first and second gate insulating films are formed from one of silicon nitride and silicon oxide.
24. (Original) The method according to claim 17, wherein the storage electrode is formed by depositing a metal from one of chromium and molybdenum using a technique from one of chemical vapor deposition and sputtering, and then patterning the metal.
25. (Original) The method according to claim 17, wherein the active layer and the ohmic contact layer are formed by depositing first and second semiconductor materials, respectively, after forming the gate insulating films, and then patterning the materials.
26. (Original) The method according to claim 25, wherein the first semiconductor material includes undoped amorphous silicon.

27. (Original) The method according to claim 25, wherein the second semiconductor material includes one of n-type and p-type amorphous silicon at a high concentration.
28. (Original) The method according to claim 17, wherein the source and drain electrodes are formed by depositing a metal layer from one of chromium and molybdenum using a technique from one of chemical vapor deposition or sputtering, and then patterning the metal.
29. (Original) The method according to claim 17, wherein the protective layer includes one of silicon nitride and silicon oxide.
30. (Original) The method according to claim 17, wherein the protective layer includes an organic insulating material having a small dielectric constant selected from one of acrylic organic compound, Teflon, benzocyclobutene, Cytop, and perfluorocyclobutane.
31. (Original) the method according to claim 17, wherein the pixel electrode and the transparent electrode pattern are formed by depositing a transparent conductive material from one of indium-tin-oxide, indium-zinc-oxide, and indium-tin-zinc-oxide on the protective layer and then patterning the transparent conductive material.